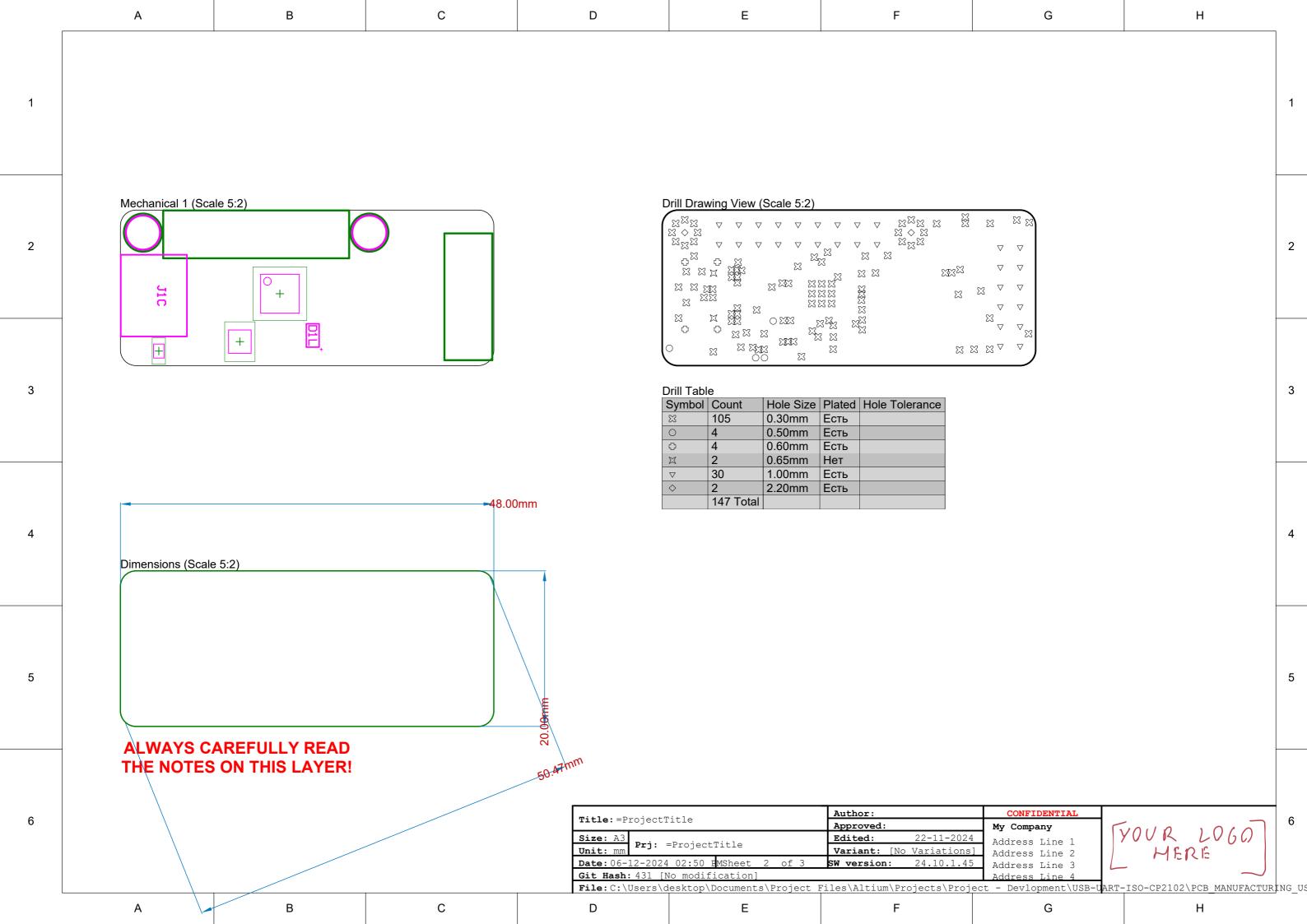
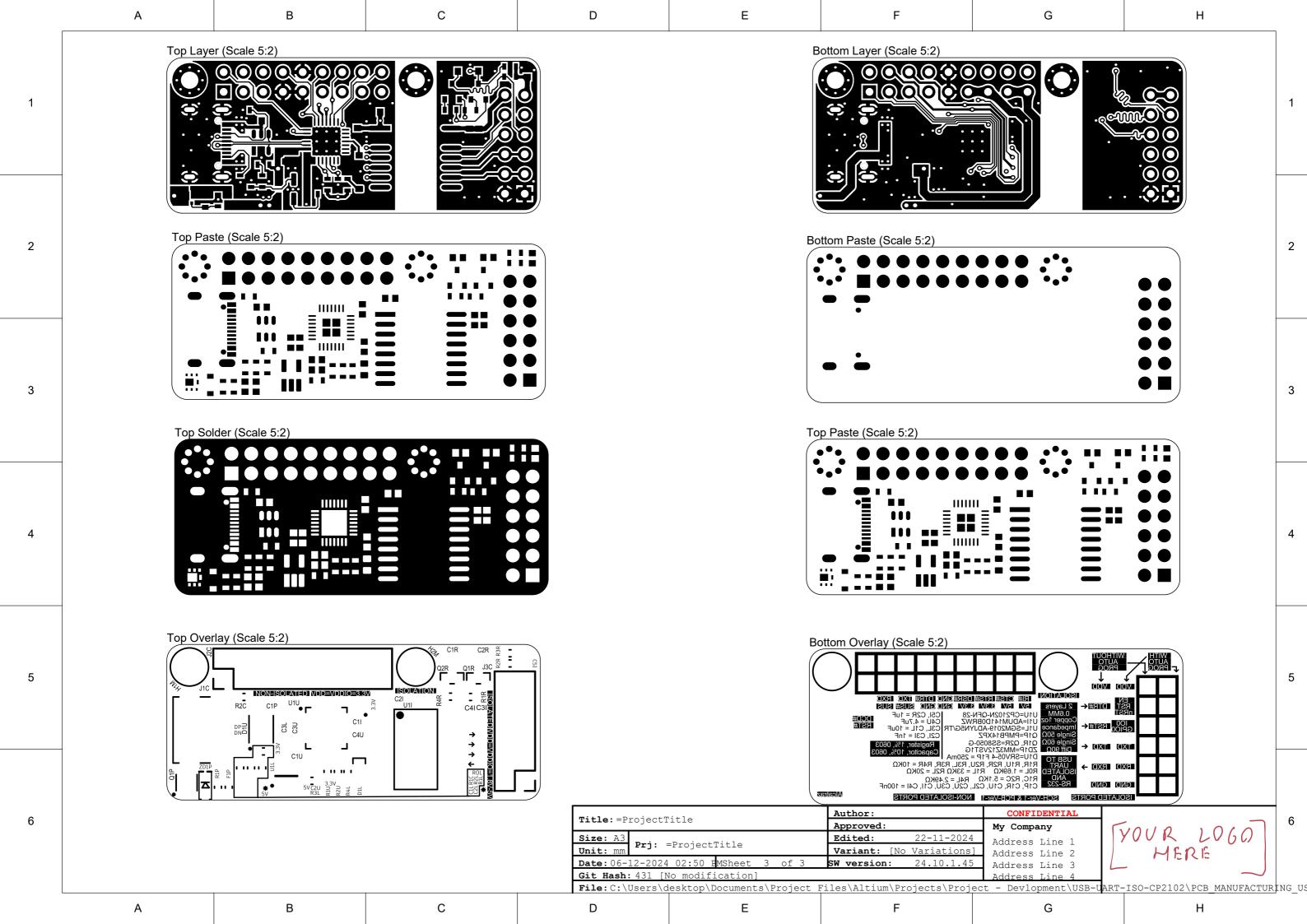
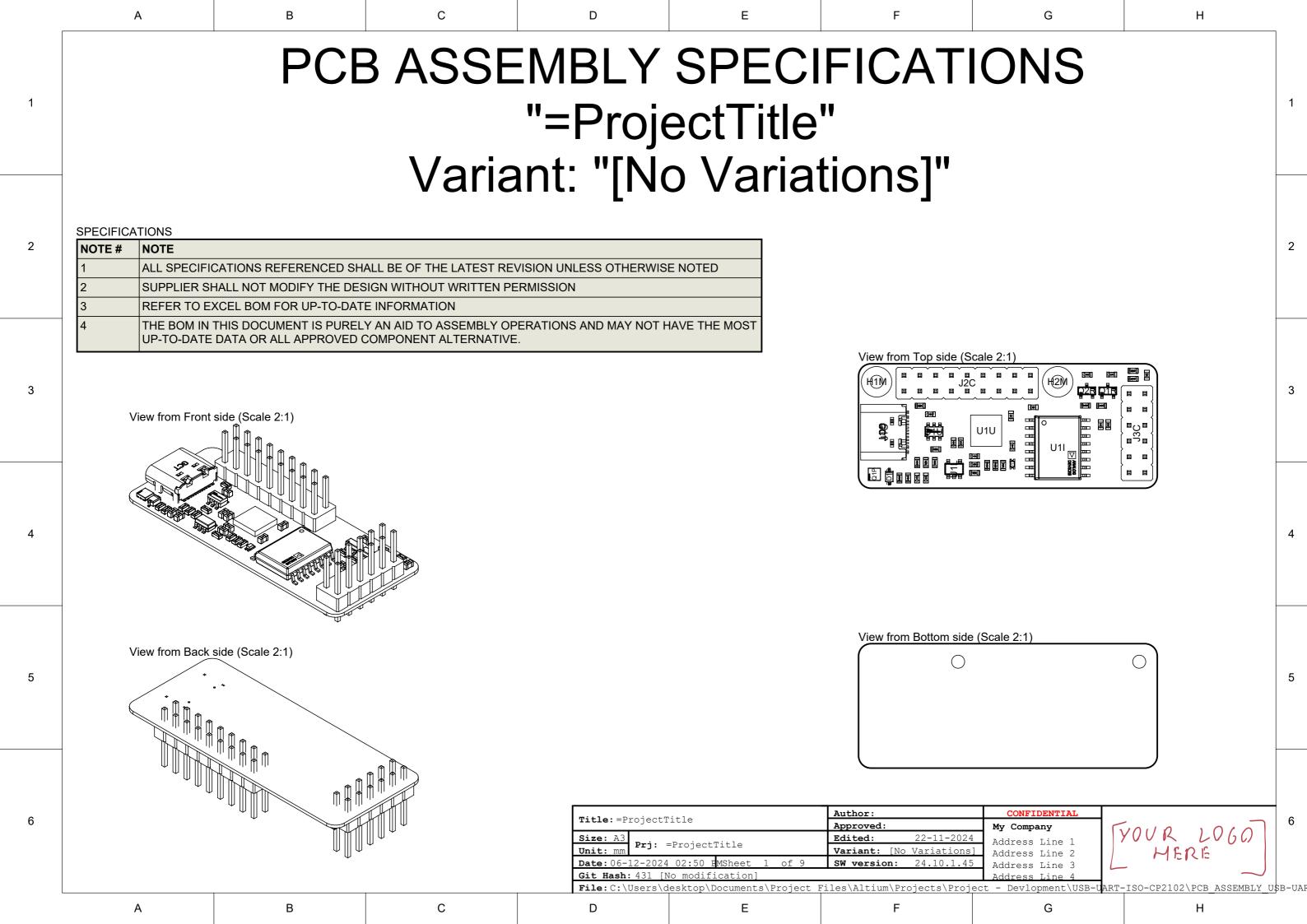
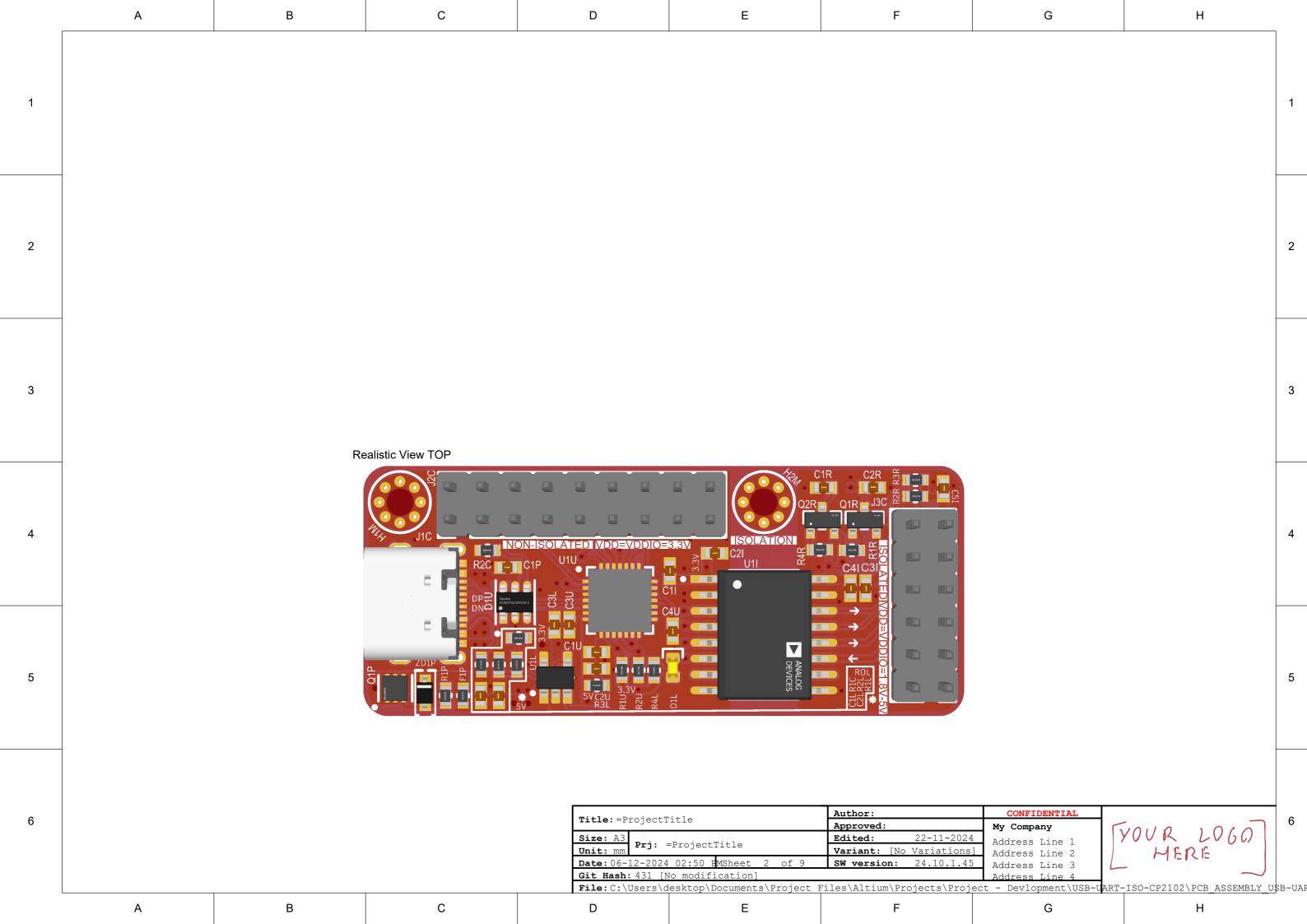


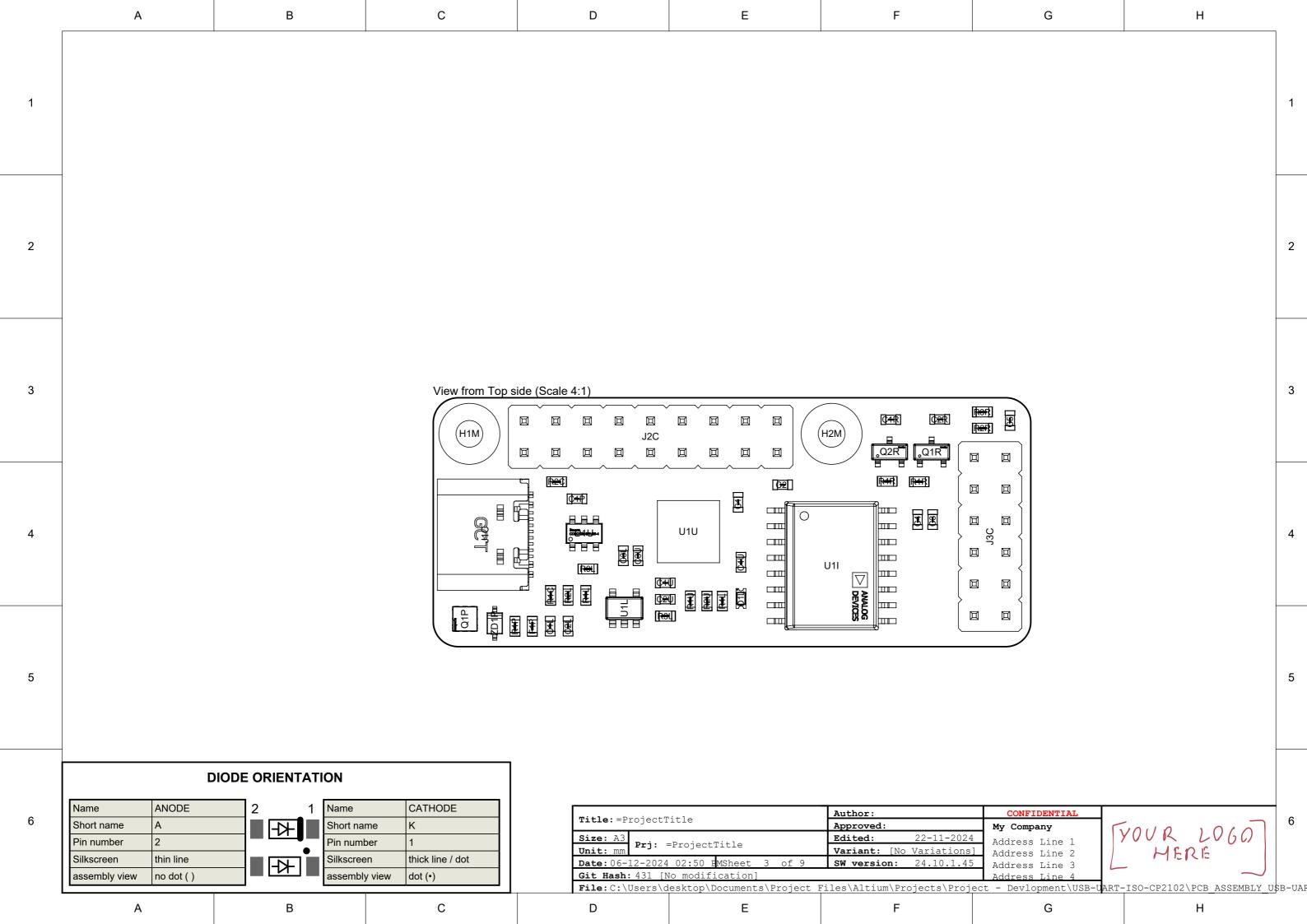
PCB MANUFACTURING SPECIFICATIONS "=ProjectTitle" **SPECIFICATIONS SPECIFICATIONS** NOTE# NOTE LENGHT 20.00mm **WIDTH** ALL SPECIFICATIONS REFERENCED ARE OF THE REVISION SPECIFIED IN THE TITLE BLOCK 48.00mm **LAYERS** SUPPLIER SHALL NOT MODIFY THE DESIGN OR APPROVED STACK-UP WITHOUT WRITTEN PERMISSION FR-4 **MATERIAL** ALL MATERIALS SHALL BE RoHS COMPLIANT AND FINAL PRODUCT SHALL BE ACCEPTABLE TO USE IN RoHS ASSEMBLY. RoHS LOGO SHALL BE MARKED IN SILKSCREEN INK BY THE SUPPLIER WHERE INDICATED BY **MATERIAL MIN TG** 130-140 THE TEXT "PLACE MARKINGS HERE" TRACK WIDTH/CLEARANCE 10 mils / 10 mils COPPER FOIL: REFER TO LAYER STACK LEGEND FOR Cu THICKNESS DETAILS. ALL Cu THICKNESSES ARE **THICKNESS** 0.6mm FINISHED AND INCLUDE BASE FOIL PLUS Cu PLATING ON PLATED LAYERS **COPPER THICKNESS** 35um (1oz) ELECTRICAL TEST: ALL PRINTED CIRCUITS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS/SHORTS USING PROVIDED NETLIST. REJECTED PRINTED BOARDS MUST BE CLEARLY MARKED WITH NON-YES, TOP AND BOTTOM SOLDERMASK CONDUCTIVE. PERMANENT INK. **GREEN SOLDERMASK COLOR** MARKINGS: VENDOR MARKING AND DATE/LOT CODES SHALL BE LOCATED ON THE BOARD IN THE SILKSCREEN YES. TOP AND BOTTOM RESERVED AREA AS SPECIFIED IN THE GERBER LAYER "PCBM NOTES" BY THE TEXT "PLACE MARKINGS SILKSCREEN COLOR WHITE MARKINGS: THE SIDE ONTO WHICH PLACE THE MARKINGS IS AT THE SUPPLIER DISCRESSION UNLESS SURFACE FINISH **HASL LEAD FREE** OTHERWISE NOTED ONTO THE LAYER "PCBM NOTES" NO **GOLD FINGERS** SUPPLIER SHALL CHECK PCBM NOTES LAYER BEFORE ASKING FOR CLARIFICATIONS **CHAMFERING** YES MANUFACTURE TENTED/PLUGGED VIAS AS SPECIFIED IN THE GERBER FILES YES IMPEDANCE CONTROL HALF-CUT/CASTELLATED HOLES NO **BURIED/BLIND VIAS** NO NO VIAS FILLED WITH RESIN Layer Stack Legend Material Layer Thickness Dielectric Material Type Gerber NO **CARBON MASK** Top Overlay GTO COUNTERSINKS/COUNTERBORES NO Surface Material Top Solder Solder Mask GTS NO **Z-AXIS MILLING** Copper Top Layer Signal GTL PEELABLE SOLDERMASK NO Core 0.50mm FR-4 Dielectric **GBL** 0.04mm Signal Solder Mask GBS Surface Material Bottom Solder 0.02mm Solder Resist GBO **Bottom Overlay** Legend Total thickness: 0.60mm NON-COPPER LAYER THICKNESS FOR REFERENCE ONLY LAYERS OF TYPE "INTERNAL PLANE" ARE NEGATIVE Author: Title: =ProjectTitle Approved: My Company Address Line 1 Prj: =ProjectTitle Variant: Address Line 2 SW version: Address Line 3 С G В

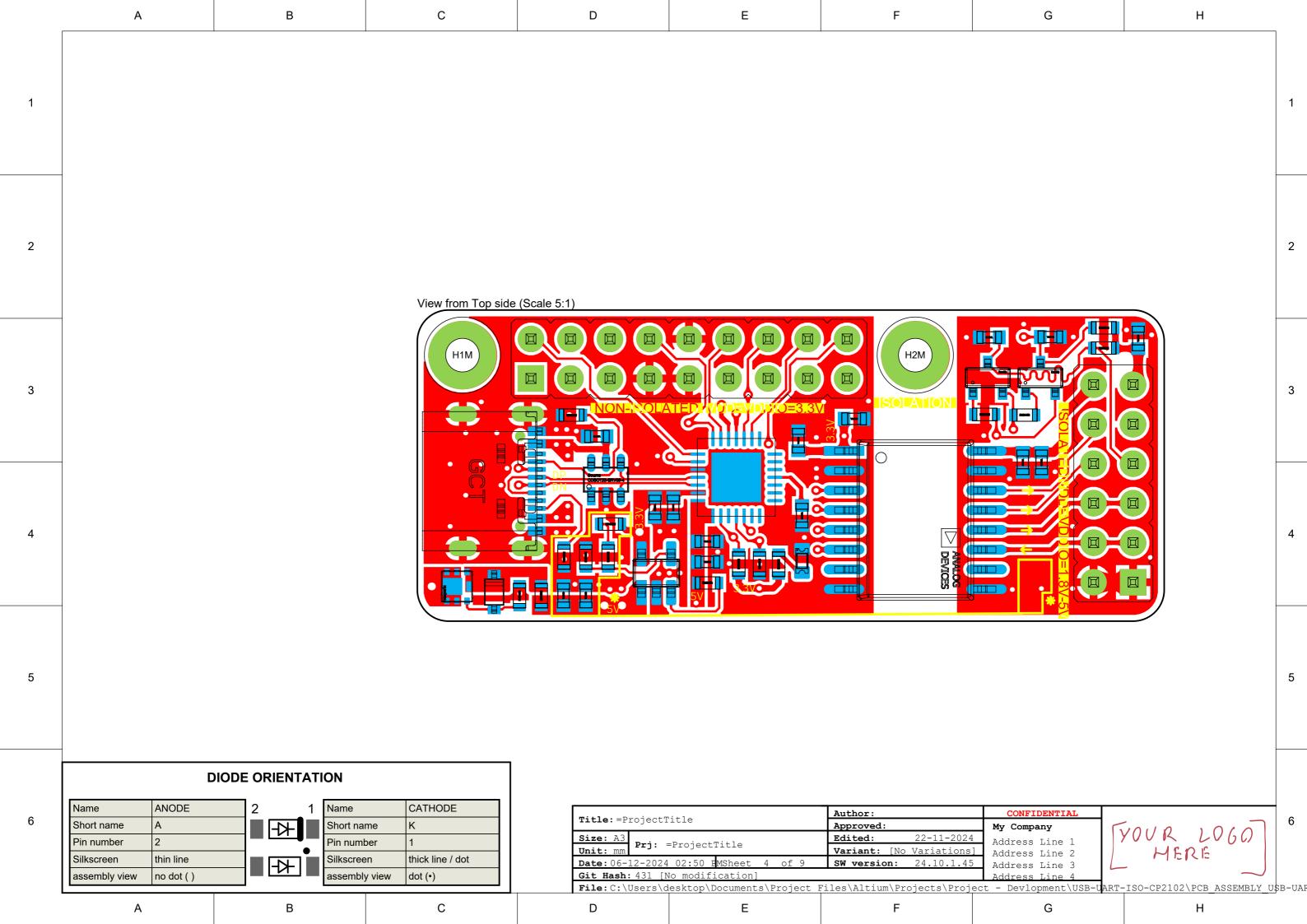


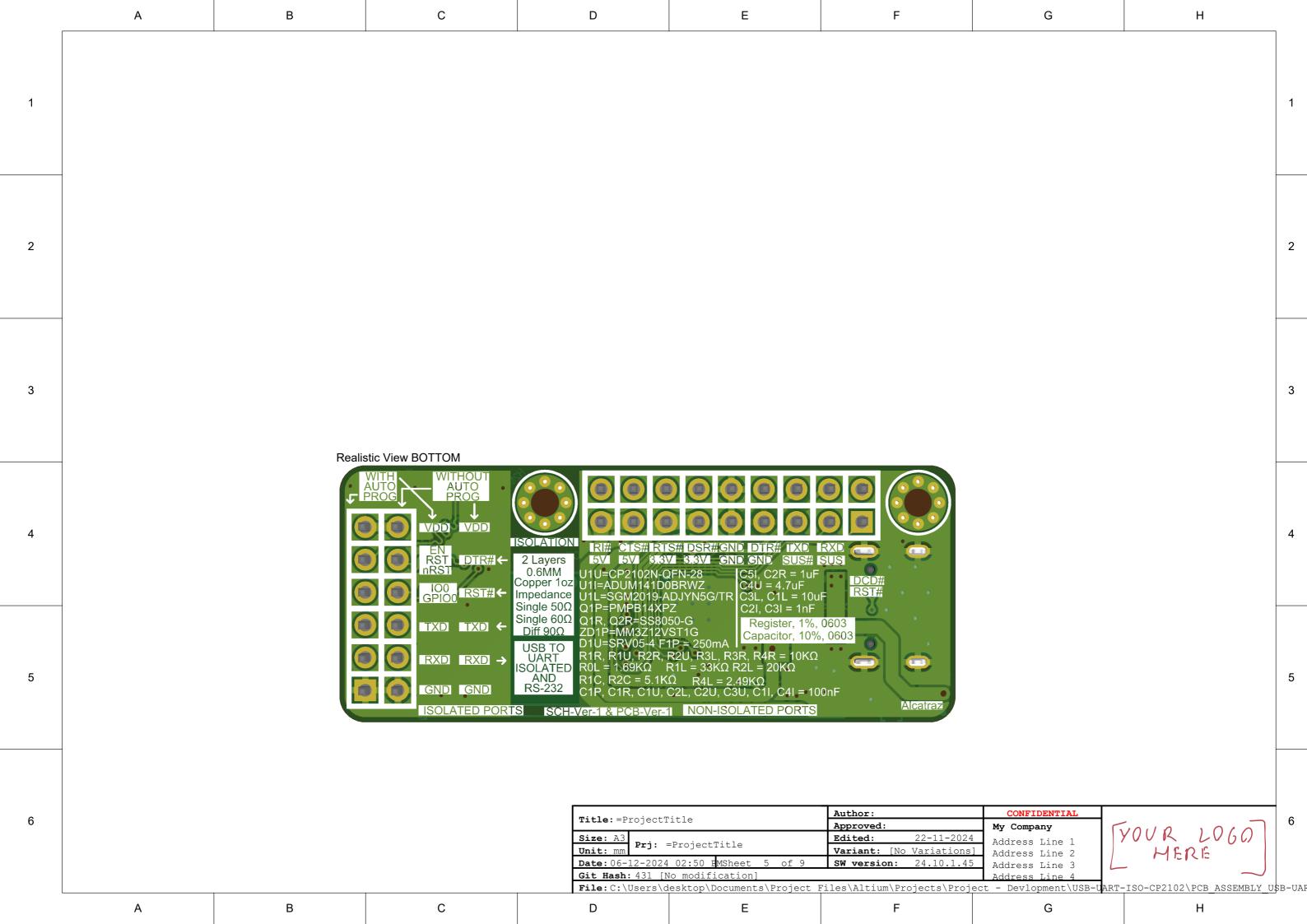


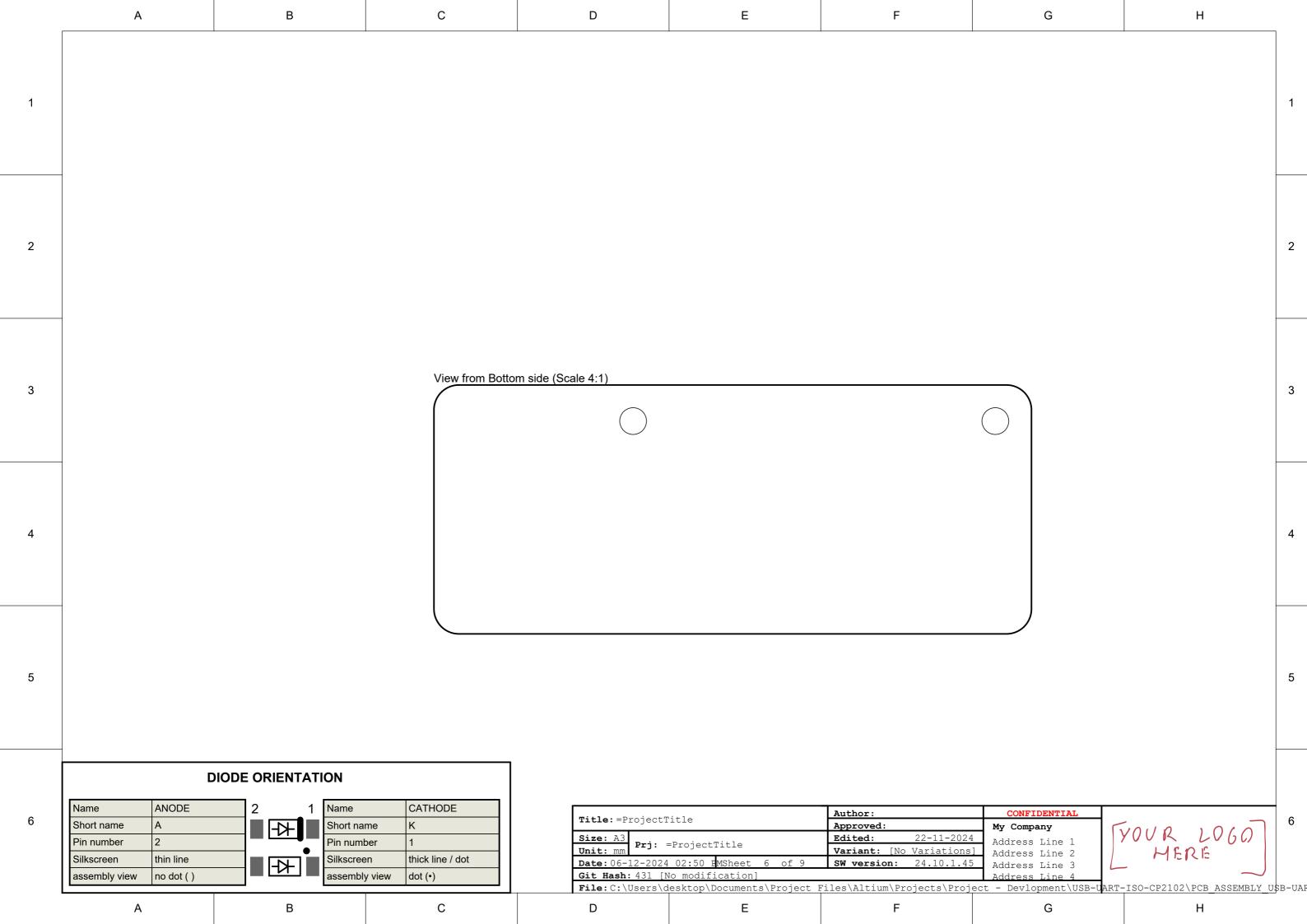


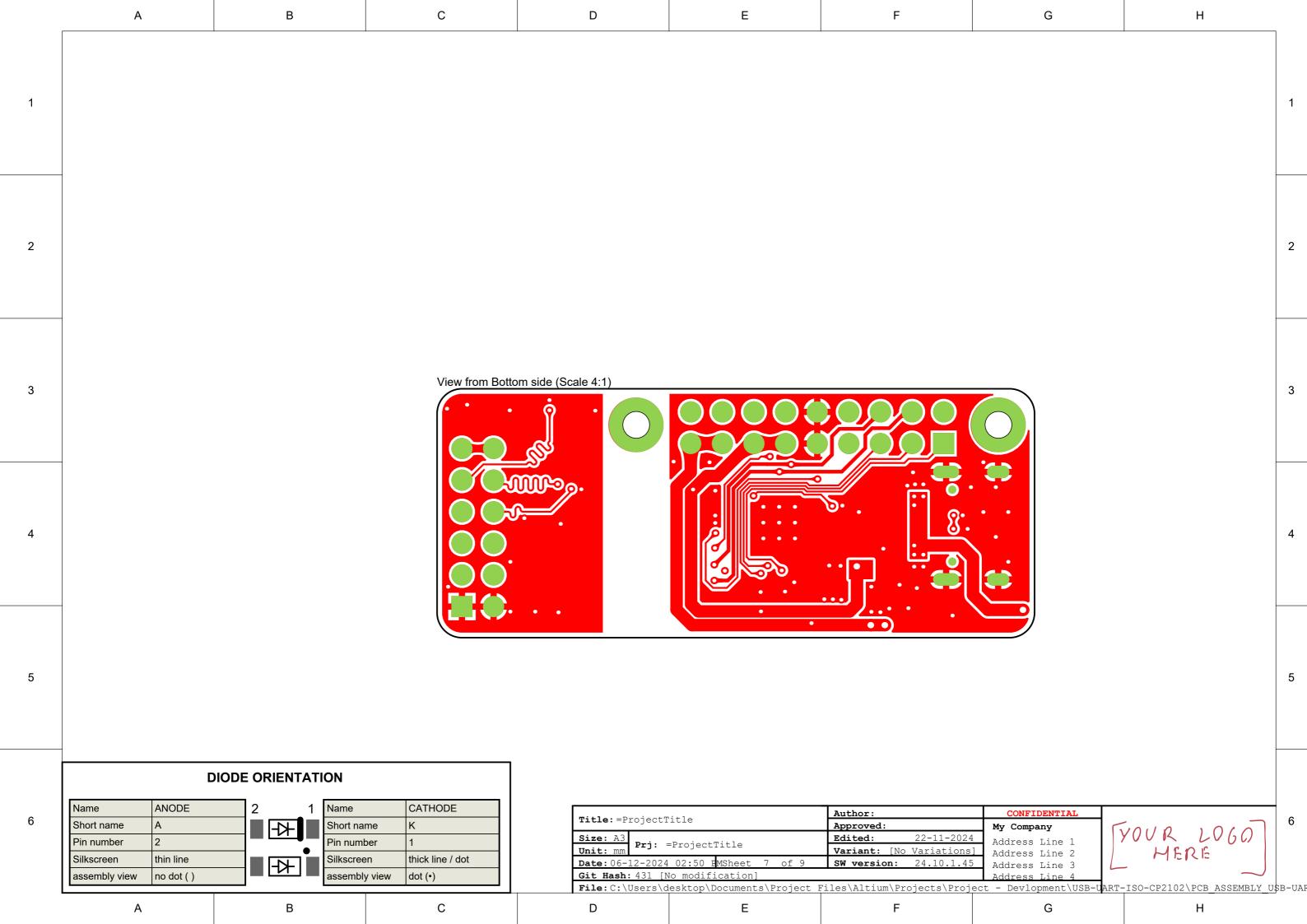


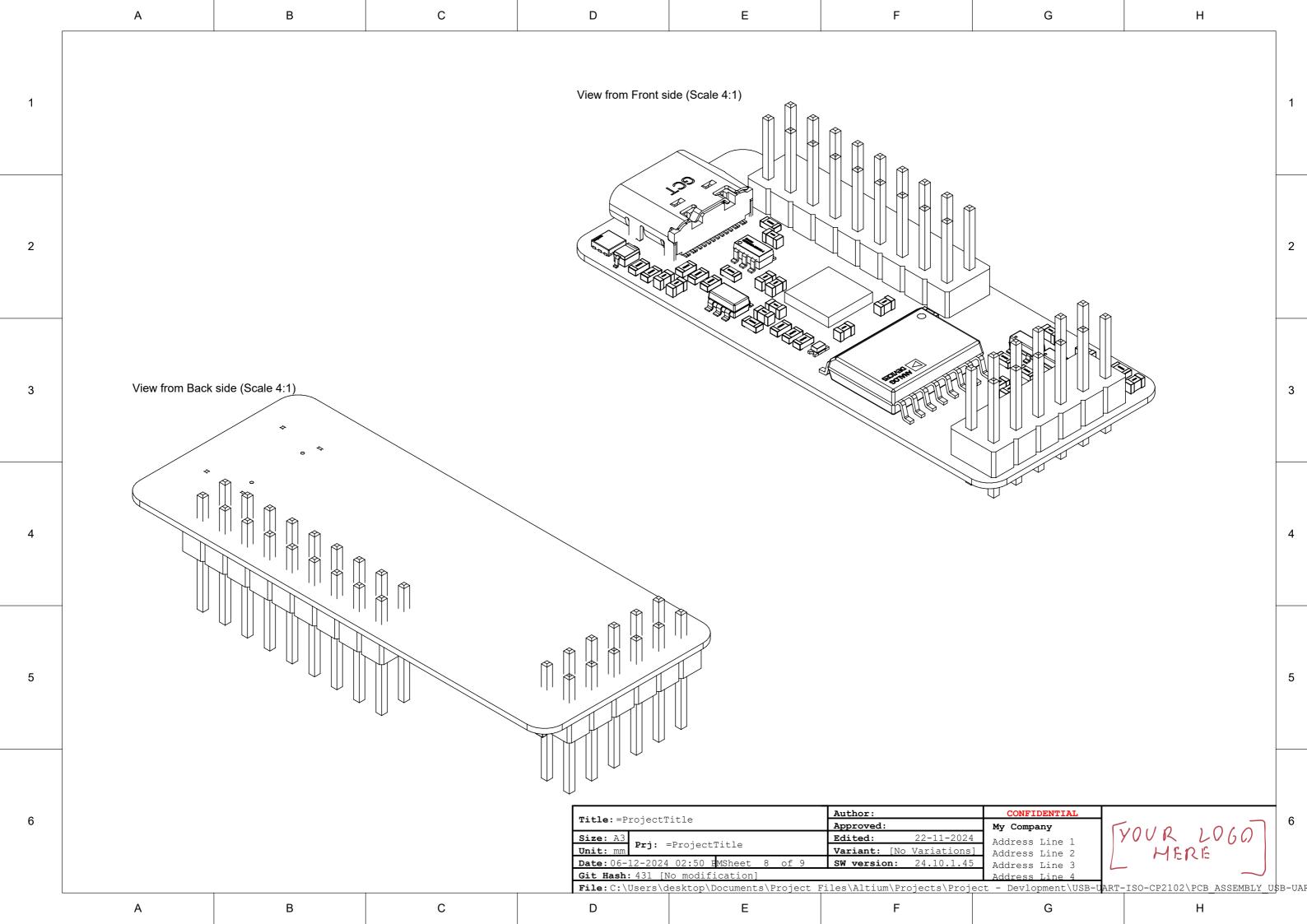












	А		В	С	D	E	F	G	Н		
1										1	
	Bill Of Ma	terials									
2	Line #		Description		Designator	Quantity	Manufacturer Part Number 1	Part Number	Layer		
		Cap Cer 0.1UF 6.3V X7R 0603		C1I, C1R, C3U	3	KGM15AR70J104KM			2		
	Multilayer Ceramic Capacitor, 10 uF, 10 V, ± 10%, X5R, 0603 [1608 Metric] Multilayer Ceramic Capacitor, 0.1 uF, 10 V, ± 10%, X7R, 0603 [1608 Metric]			C1L C1P, C1U, C2L, C2L	J. C4I 5	C0603C104K8RAC786					
	Cap Ceramic 0.001uF 6.3V C0G 10% SMD 0603 125°C Paper T/R			C2I	1	7					
		Ceramic Capacitor, Multilayer, Ceramic, 10V, 10% +Tol, 10% -Tol, X5R, 15% TC, 1uF, 0603			C2R, C5I	2					
			eramic 0.001uF 10V X7R 10% SME Ceramic Capacitor, 10 uF, 6.3 V, ± 1		C3I C3L	1	CL10A106KQ8NNNC				
			Ceramic Capacitor, 4.7 uF, 10 V, ± 1	0%, X5R, 0603 [1608 Metric]	C4U	1	CL10A475KP8NNNC				
3			LED 0603 YELLOW S TVS DIODE 5V 15V SC		D1L D1U	1					
			Fuse PPTC SMD 06	03	F1P	1				3	
		USB Connector Type C SMT 16 Pin (Power pins joints = 12 pins)		J1C	1						
					J2C J3C	1					
			PMPB14XPZ		Q1P	1	PMPB14XPZ				
		Trans Gp Bjt NPN 25V 1.5A 300MW 3-PIN SOT-23 T/r Surface Mount Thick Film Chip Resistor 0603 Case 1.69K Ohms 1% Tolerance 100			Q1R, Q2R	2	SS8050-G				
4		PPM SMD Chip Resistor, 5.1 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose Res Thick Film 0603 33K Ohm 1% 0.1W(1/10W) ±100ppm/C Pad SMD Automotive T/R SMD Chip Resistor, 100 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose SMD Chip Resistor, 10 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose SMD Chip Resistor, 20 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose Res Thick Film 0603 2.49K Ohm 1% 1/10W ±100ppm/°C Molded SMD SMD Paper		R0L	1	MCR03EZPFX1691					
				R1C, R2C	2	CRCW06035K10FKEA					
				R1L	1	ERJ-3EKF3302V			4		
				R1P	1	AC0603FR-07100KL					
					R1R, R1U, R2R, R2U, R3L	., R3R, R4R 7	RC0603FR-0710KL				
				R2L	1	CR0603-FX-2002ELF					
5		Res Thick Film	T/R		R4L	1					
			DGTL ISO 3750VRMS 4CH (LDO U-Reg Adj 0, 3A SO		U1I U1L	1					
		Single-Chip U	ISB to UART Bridge, 1024 Bytes El	EPROM, -40 to 85 degC, 28-pin	U1U	1					
		MM3Z12V	QFN, Tube ST1G Zener Diode, 12V 2% 200 m		ZD1P	1				5	
	Semiconductor MM3Z12VST1G			 ··							
	Please consider LCSC (立创商城) as our first supplier BOM FOR REFERENCE ONLY ALWAYS REFER TO THE LATEST EXCEL BOM PROVIDED				millor During 112		Author:	CONFIDENTIAL	T		
6					<pre>Title: =ProjectTitle Size: A3 Unit: mm Prj: =ProjectTitle</pre>		Approved:	My Company	TYPUP 10	YOUR LOGO 6	
							Edited: 22- Variant: [No Var	-11-2024 Address Line 1 iations] Address Line 2	HERE HERE	001	
					Date: 06-12-2024				L Mrke		
	ALWAYS R	EFER TO T	HE LATEST EXCEL BOM	PROVIDED		<pre>Git Hash: 431 [No modification] File:C:\Users\desktop\Documents\Project Files\Altium\Project</pre>			IIART-ISO-CD2102\DCD AGG	SEMBIV IICP-II	
l	A	A B C			D D	E	F FITES (ATCTUM (Projec	G G	H	эгмогт [_] ∩bR-∩ <i>E</i>	